

List of Current Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-32 (Cancelled).

33. (Previously presented) The method as claimed in claim 65, further comprising the step of:

applying solder paste to solder contact surfaces provided on the second side of the circuit board for a populating of the second side of the circuit board with at least one SMD-component, wherein:

following populating of the second side of the circuit board with the SMD-component, it is soldered, together with the connection wire of the THT-component, in the reflow oven.

34. (Previously presented) The method as claimed in claim 66, further comprising the step of:

applying solder paste to solder contact surfaces provided on the second side of the circuit board for a populating of the second side of the circuit board with at least one SMD-component, wherein:

following populating of the second side of the circuit board with the SMD-component, it is soldered, together with the connection wire of the THT-component, in the reflow oven.

35. (Previously presented) The method as claimed in claims 65, wherein:
the first side of the circuit board is populated with at least one SMD-component.

36. (Previously presented) The method as claimed in claim 66, wherein:
the first side of the circuit board is populated with at least one SMD-component.

37. (Previously presented) The method as claimed in claim 35, further comprising the steps of:

- printing of solder paste on the first side of the circuit board;
- populating of the first side with SMD-components;
- soldering the SMD-components of the first side in the reflow oven;
- populating of the first side with at least one THT-component;
- printing of solder paste on the second side;
- populating the second side with SMD-components, and
- soldering SMD-components of the second side and the one or more THT-components in the reflow oven.

Claims 38 - 40 (Cancelled).

41. (Previously presented) The method as claimed in claim 37, wherein:
before the populating of the THT-components on the locations to be populated, adhesive for securing the THT-components on the circuit board is applied.

42. (Previously presented) The method as claimed in claim 37, wherein:
on the circuit board and/or on at least one of the THT-components, at least one securement aid is provided, which secures the affected THT-component mechanically on the circuit board following the populating.

43. (Previously presented) The method as claimed in claim 42, wherein:
the securement aid includes a snap-in mechanism.

44. (Previously presented) The method as claimed in claim 35, further comprising the steps:

- printing of solder paste on the first side;
- applying adhesive on the locations of the first side which are to be populated with THT-components;
- populating the first side with SMD-components;
- populating the first side with THT-components;
- soldering the SMD-components of the first side in the reflow oven;
- printing solder paste on the second side;
- populating the second side with SMD-components, and
- soldering the components of the second side and the THT-components in the reflow oven.

Claims 45-48 (Cancelled).

49. (Previously presented) The method as claimed in claim 65, wherein: the first side of the circuit board populated with the one or more THT-components is cooled in the reflow oven.

Claims 50 - 64 (Cancelled).

65. (Previously presented) A method for populating and soldering a circuit board having a first side and a second side and at least one wired, electrical component ("THT-component") having at least one connection wire or connection pin and a housing or casing thermally critical for conventional, automatic soldering technology, comprising the steps of:

- populating the first side of the circuit board with the at least one wired, electrical THT-component, with the connection wire or pin stuck from the first side through a hole and emerging on the second side of the circuit board in the area of a soldering contact surface printed with a solder paste;

placing the circuit board so populated into a reflow oven for the soldering;
and

at least partially shielding the first side populated with the THT-component, by the circuit board itself, from a heat or energy feed effecting the soldering, in the reflow oven, from the heat or energy feed acting on the second side for the soldering, wherein:

in an essentially horizontal arrangement of the circuit board during travel through the reflow oven for the soldering the THT-components are located underneath the circuit board.

66. (Previously presented) A method for populating and soldering a circuit board having a first side and a second side and at least one wired, electrical component ("THT-component") having at least one connection wire or connection pin and a housing or casing thermally critical for conventional, automatic soldering technology, comprising the steps of:

populating the first side of the circuit board with the at least one wired, electrical THT-component, with the connection wire or pin stuck from the first side through a hole and emerging on the second side of the circuit board in the area of a soldering contact surface printed with a solder paste;

placing the circuit board so populated into a reflow oven for the soldering;
thermally separating the first side populated with the THT-component, by the circuit board itself, from the heat or energy feed acting on the second side of the circuit board for the soldering; and

achieving a temperature difference of at least 28°C between the first side and the second side, and wherein:

in an essentially horizontal arrangement of the circuit board during travel through the reflow oven for the soldering of the THT-components or the THT-component, these or this, as the case may be, are located underneath the circuit board.